



(19)

(11) Publication number: 2001011494 A

Generated Document

PATENT ABSTRACTS OF JAPAN

(21) Application number: 11180291 (51) Intl. Cl.: C11D 7/50 C11D 7/26 C11D 7/34 C11D 7/60 C11D 17/08 H01L 21/312 H05K 3/28

(22) Application date: 25.06.99

(30) Priority:

(43) Date of application publication: 16.01.01

(84) Designated contracting states:

(71) Applicant: SHOWA DENKO KK

(72) Inventor: TSUTSUI YUICHI

(74) Representative:

(54) CLEANING LIQUID FOR
POLYIMIDE PRECURSOR
COMPOSITION AND
SURFACE PROTECTIVE
FILM USING THE SAME OR
METHOD FOR FORMING
INTERLAMINAR
INSULATING FILM

(57) Abstract:

PROBLEM TO BE SOLVED: To
provide a high safety cleaning liquid
for polyimide precursor compositions

2001011494 A

which can easily remove a polyimide precursor composition entered into the back of a semiconductor substrate and the like in spinning coating the polyimide precursor composition on the surface of the semiconductor substrate and the like and, at the same time, bring about an effect of reducing the height of a build-up which is composed of the polyimide precursor composition and caused at the end portions of the surface of a substrate upon spinning coating.

SOLUTION: A cleaning liquid for polyimide precursor compositions comprising a sulfur-containing organic solvent or a sulfur-containing organic solvent and a poor solvent for the polyimide precursor compositions is used. Preferably, dimethyl sulfoxide is used as the sulfur-containing organic solvent. Preferably, the cleaning liquid for polyimide precursor compositions having a solidifying point of 18.5°C to -80°C is used.

COPYRIGHT: (C)2001,JPO